



Final Product/Process Change Notification

Document #:FPCN25224Z

Issue Date:10 Aug 2023

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|---|--|----------------------|
| Title of Change: | Qualification of onsemi Aizu Japan as wafer Fab for ONC25BCD Technology for select products in NCV20071 family | |
| Proposed Changed Material First Ship Date: | 12 Feb 2024 or earlier if approved by customer | |
| Current Material Last Order Date: | N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i> | |
| Current Material Last Delivery Date: | N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i> | |
| Product Category: | Active components – Integrated circuits | |
| Contact information: | Contact your local onsemi Sales Office or Adrian.Croitoru@onsemi.com | |
| PCN Samples Contact: | Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. | |
| Sample Availability Date: | 30 Jun 2023 | |
| PPAP Availability Date: | 25 Aug 2023 | |
| Additional Reliability Data: | Contact your local onsemi Sales Office or Vladislav.Hrachovec@onsemi.com | |
| Type of Notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com . | |
| Change Category | | |
| Category | Type of Change | |
| Process - Wafer Production | Move of all or part of wafer fab to a different location/site/subcontractor | |
| Description and Purpose: | | |
| <p>onsemi would like to inform its customers of qualification of a wafer fabrication facility for ONBCD25 technology at onsemi Aizu, Japan for the devices listed in this FPCN. All products listed here will be sourced only from onsemi Aizu.</p> <p>There is no change to the orderable part number.</p> <p>There is no product marking change as a result of this notification.</p> | | |
| NCV20071 FAMILY – TSOP-5 and SOT553 packages | From | To |
| Wafer Fab | onsemi, Gresham, Oregon (US) | onsemi, Aizu (Japan) |



| Reason / Motivation for Change: | Capacity Improvement | | | |
|---|---|--|----------|---------|
| Anticipated impact on fit, form, function, reliability, product safety or manufacturability: | The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts. | | | |
| Sites Affected: | | | | |
| onsemi Sites | | External Foundry/Subcon Sites | | |
| onsemi Aizu, Japan | | None | | |
| onsemi, Gresham United States | | | | |
| Marking of Parts/ Traceability of Change: | Custom source information will be updated on product label. Product traceability will be identified by encoded date code. | | | |
| Reliability Data Summary: | | | | |
| QV DEVICE NAME: NCV20072DR2G RMS: O86311 PACKAGE: SOIC-8 | | | | |
| Test | Specification | Condition | Interval | Results |
| High Temperature Operating Life | JESD22-A108 | Ta=125°C, 100 % max rated Vcc | 1008 hrs | 0/77 |
| High Temperature Storage Life | JESD22-A103 | Ta= 150°C | 1008 hrs | 0/77 |
| Early Life Failure Rate | JESD22-A108 | Ta=125°C, 100 % max rated Vcc | 48 hrs | 0/800 |
| Preconditioning | J-STD-020 JESD-A113 | MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only | | 0/all |
| Temperature Cycling | JESD22-A104 | Ta= -55°C to +150°C | 1000 cyc | 0/77 |
| Highly Accelerated Stress Test | JESD22-A110 | 130°C, 85% RH, 18.8psig, bias | 96 hrs | 0/77 |
| Unbiased Highly Accelerated Stress Test | JESD22-A118 | 130°C, 85% RH, 18.8psig, unbiased | 96 hrs | 0/77 |
| Refer to the attached AEC1 Pager for more details. | | | | |
| To view attachments: | | | | |
| <ol style="list-style-type: none"> 1. Download pdf copy of the PCN to your computer 2. Open the downloaded pdf copy of the PCN 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field 4. Then click on the attached file. | | | | |
| Electrical Characteristics Summary: | | | | |
| Electrical characteristics are not impacted. | | | | |



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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

| Current Part Number | New Part Number | Qualification Vehicle |
|---------------------|-----------------|-----------------------|
| NCV20071XV53T2G | NA | NCV20072DR2G |
| NCV20071SN2T1G | NA | NCV20072DR2G |